	CONNECTING CS INDUSTRIES® MALETING CS INDUSTRIES® MALETIAL COMP	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat he declaration	ion of the encompas	e substances sses all lowe	within the er level mat	manufactur erials for wh	er listed it hich the m	em. Note: if anufacturer	f the item is an as has engineering	ssembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type Distribute	Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogene				eous Materia	Materials and Mfg Information					
Supplie	r Information															
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*					
nsemi											2024-04-25					
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*						
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*						
Product-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item FCH76N		Number Mfr Item Name				Effective Date Version Manufacturing 2024-04-25 CP8		ing Site	Weight* 5456.725		UOM	Unit Type			
			60N	0N SM 600V 36mOhm f TO247								mg	Each			
/Ianufa	cturing Proccess Informa	tion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		J-STD-020 MS	L Rating	Peak Process Body Temperate		ure Max Time at Peak Tem		Temperatu	ire Numb	er of Reflow Cyc	cles		
Matte Tin (Sn) - annealed		U Alloy NA			0 C		30		second	ls 3						
omments	3															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
lead Frame	3612.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.75	mg
			В	Nickel (Ni)	7440-02-0		117.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.1	mg
			Supplier	Copper (Cu)	7440-50-8		3489.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	ack 1739.8	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4- hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		20.9	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		283.9998	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		34.9	mg
			Supplier	Carbon Black (C)	1333-86-4		17.3999	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1382.6	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg